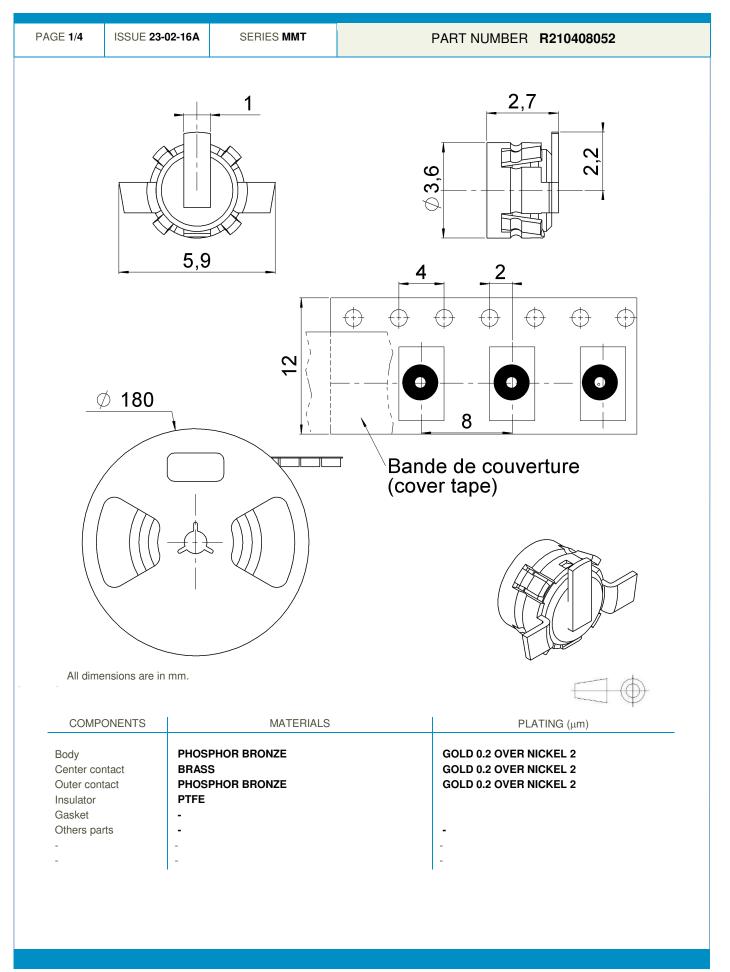
STRAIGHT JACK RECECPTACLE SMT TYPE - GOLD 0.2 - REEL OF 500



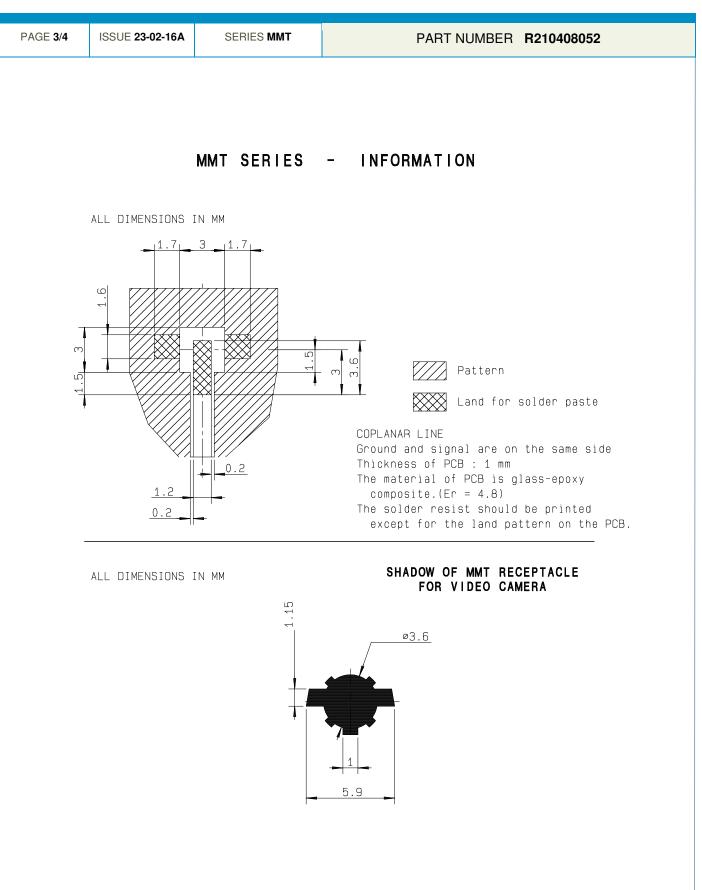
Radiall 🚺

STRAIGHT JACK RECECPTACLE SMT TYPE - GOLD 0.2 - REEL OF 500

PAGE 2/4	ISSUE 23-02-16A	SERIES MMT		PART	NUMBER	R210408	3052			
PACKAGING										
		Standard 500		Unit Contact us		her act us				
ELECTRICAL CHARACTERISTICS					ENVIRO	ONMENTAL				
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating Dielectric withstan Insulation resistan	- (Iding voltage	$\begin{array}{cccc} {\bf 50} & \Omega \\ {\bf 0-8} & {\rm GHz} \\ {\bf 0,0500} & x \ {\rm F}({\rm GHz}) \ {\rm Maxi} \\ {\bf 0.20} & \sqrt{{\rm F}({\rm GHz})} \ {\rm dB} \ {\rm Maxi} \\ {\bf NA} & - \ {\rm F}({\rm GHz})) \ {\rm dB} \ {\rm Maxi} \\ {\bf 170} & {\rm Veff} \ {\rm Maxi} \\ {\bf 500} & {\rm Veff} \ {\rm mini} \\ {\bf 5000} & {\rm M}\Omega \ {\rm mini} \end{array}$	axi Iaxi	Operating temperature Hermetic seal Panel leakage		FICATION	-55/+100 NA NA	°C Atm.cm3/s		
M	ECHANICAL CHAR	ACTERISTICS			CABLE	ASSEMBLY				
Center contact ret Axial force – Ma Axial force – Op	ating End	NA N mini NA N mini		Stripping a mm 0	b c 0 0		e 0	f 0		
Torque		NA N.cm min	ni	Assembly instruction:						
Recommended to Mating Panel nut Clamp nut A/F clamp nut	rque	NA N.cm NA N.cm NA N.cm 0,0000 mm		Recommended cable	(s)					
Mating life Weight		500 Cycles mini 000 g								
Characteristics indicated on this data sheet are those that can be achieved with the performance cable. Intrinsic limitations of the cable may diminish the performance assembly										
				Cable retention						
				- pull off - torque		NA NA				
TOOLING										
Part Number Description			iption			Hexagon				
			HAR	ACTERISTICS						
OTHER CHARACTERISTICS accouplt : 18Nmax / desacc. : 7Nmin										

Radiall 💓

STRAIGHT JACK RECECPTACLE SMT TYPE - GOLD 0.2 - REEL OF 500



Radiall 🚺

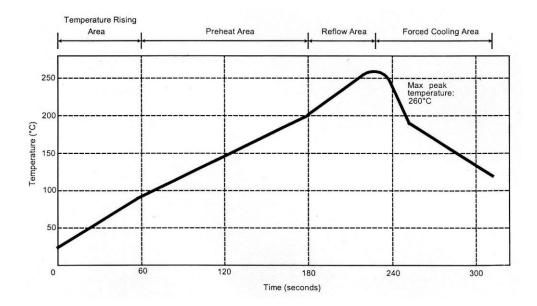


STRAIGHT JACK RECECPTACLE SMT TYPE - GOLD 0.2 - REEL OF 500

PAGE 4/4	ISSUE 23-02-16A	SERIES MMT	PART NUMBER R210408052					
SOLDER PROCEDURE OF MMT RECEPTACLE IN INDUSTRIAL ENVIRONMENT								
 1 – Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application. We recommend a Low Residue Solid Flux. We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the prined zone are clean. 								
 2 – Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type. A video camera is recommanded for positioning of the component. (see page 3) Adhesive agents must not be used on the receptacle. 								
0	y infra-red reflow. ase find the typical pro	file to use.						
4 – Cleaning of printed circuit boards								

5 - Verification of solder joints and position of the component by visual inspection

Note : The MMT receptacle and the MMT plug must not be mated before completion of this procedure.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec